





#### Description

Current Limiting Module (CLM) is a chip type surface mountable device that can protect against both overcurrent and overcharging. It comprises a fuse element to ensure stable operation under normal electrical current and to cut off the current when overcurrent occurs. It also comprises a resistive heating element that could be used in combination with a voltage detecting means, such as IC and FET. When overvoltage is detected, the heating element is electrically excited to generate heat to blow the fuse element to achieve overvoltage protection.

#### Features

- Halogen-free
- Overcharging protection
- Overcurrent protection

#### Application

- Self Balancing
- E-Bike
- Power Tool

• Automotive applications

Surface mountable

· Fast response time

- Energy Storage systems
- Drone

#### Agency Approval and Environmental Compliance



Regulation Halogen Free

Standard IEC 61249-2-21:2003

#### **Electrical Specifications**

Devit Nevrelsen		V <sub>max</sub>	V <sub>max</sub> I <sub>break</sub> (V <sub>DC</sub> ) (A)	Vop (V)	Resistance		Agency Approval		
Part Number		(V <sub>DC</sub> )			R <sub>heater</sub> (Ω)	R <sub>fuse</sub> (mΩ)	c <b>AL</b> 'us	LÜVRheinland	
CLM3820P1245-RC	45	3	62	120	9.8 ~ 13.5	1.9 ~ 3.4	0.4 ~ 2.0	~	-
CLM3820P1445-RC	45	4	62	120	13.0 ~ 18.4	3.4 ~ 6.0	0.4 ~ 2.0	~	-
CLM3820P2045-RC	45	5	62	120	16.7 ~ 23.5	5.6 ~ 9.9	0.4 ~ 2.0	~	-
CLM3820P3045-RC	45	6~7	62	120	22.3 ~ 31.5	10.0 ~ 17.7	0.4 ~ 2.0	~	-
CLM3820P4045-RC	45	9~10	62	120	33.0 ~ 46.9	22.0 ~ 38.7	0.4 ~ 2.0	~	-
CLM3820P5045-RC	45	12~14	62	120	43.7 ~ 62.0	38.5 ~ 68.0	0.4 ~ 2.0	~	-







#### **Electrical Characteristics**

Current Capacity	100% x I <sub>rated</sub> No Melting
Cut Time	200% x I <sub>rated</sub> < 1 min
Over Voltage Operation	In operation voltage range, the fusing time is <1min.

#### **Note on Electrical Specifications & Characteristics**

- Vocabulary
  - $I_{rated}$  = Current carrying capacity that is measured at 40°C thermal equilibrium condition.
  - Ibreak = The current that the fuse element is able to interrupt.
  - $V_{max}$  = The maximum voltage that can be cut off by fuse.
  - **R**<sub>heater</sub> = The resistance of the heating element.
  - **R**<sub>fuse</sub> = The resistance of the fuse element.
  - Cells in series = Number of battery cells connected in series in the circuit for CLM device to protect.
- Value specified is determined by using the PWB with 29.4mm\*2oz copper traces, and 0.6mm glass epoxy PCB.
- Specifications are subject to change without notice.

### **A**WARNING

#### General

- Before and after mounted, the ultrasonic-cleaning or immersion-cleaning must not be done to CLM device. The flux on element would flow, and it would not be satisfied its specification when cleaning is done. In addition, a similar influence happens when the product comes in contact with cleaning-solution. These products after cleaning will not be guaranteed.
- Silicone-based oils, oils, solvents, gels, electrolytes, fuels, acids, and the like will adversely affect the properties of CLM devices, and shall not be used or applied.
- Please Do Not reuse the CLM device removed by the soldering process.
- CLM devices are secondary protection devices and are used solely for sporadic, accidental over-current or over-temperature error condition, and shall NOT be used if or when constant or repeated fault conditions (such fault conditions may be caused by, among others, incorrect pin-connection of a connector) or over-extensive trip events may occur.
- Operation over the maximum rating or other forms of improper use may cause failure, arcing, flame and/or other damage to the CLM devices.
- The performance of CLM devices will be adversely affected if they are improperly used under electronic, thermal and/or mechanical procedures and/or conditions non-conformant to those recommended by manufacturer.
- Customers shall be responsible for determining whether it is necessary to have back-up, failsafe and/or fool-proof protection to avoid or minimize damage that may result from extra-ordinary, irregular function or failure of CLM devices.
- There should be minimum of 0.1mm spacing between CLM and surrounding compounds, to maintain the product characteristics and avoid damage other surrounding compounds.
- This product is designed and manufactured only for general-use of electronics devices. We do not recommend that it is used for the applications Military, Medical and so on which may cause direct damages on life, bodies or properties.



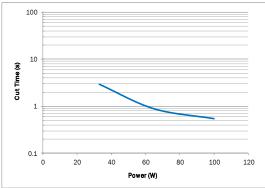


#### **Thermal Derating Characteristics**

Ambient Temperature (°C)	25	40	60
Recommend Rated Current (A)	49.0	44.5	37.0

#### **Cut Time by Heater Operation**

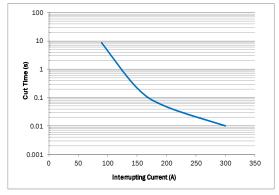
■ Various heater wattage at 25°C ambient temperature.



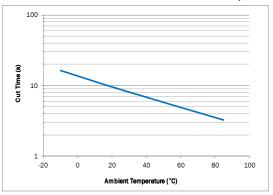
#### Constant heater wattage at various ambient temperature. 100 **-**33W -100W 10 Cut Time (s) 1 0.1 100 -20 0 40 20 60 80 Ambient Temperature (°C)

#### **Cut Time by Current Operation**

■ Various interrupting current at 25°C ambient temperature.



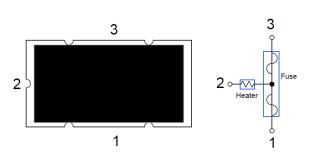
Constant 2x rated current at various ambient temperature.







**Device Circuit** 



### Physical Dimensions (mm.)

9.50 ± 0.2

 $5.00 \pm 0.3$ 

2.00 max

 $0.89 \pm 0.1$ 

 $6.54 \pm 0.1$ 

 $1.47 \pm 0.1$ 

 $1.11 \pm 0.1$ 

 $7.32 \pm 0.1$ 

Α

В

С

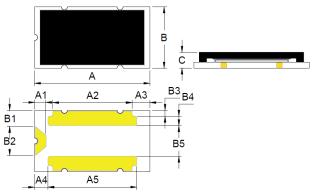
A1

A2

А3

A4

Α5



**B1** 

B2

В3

Β4

B5

 $1.32 \pm 0.1$ 

 $2.36 \pm 0.1$ 

 $0.48 \pm 0.1$ 

 $0.77 \pm 0.1$ 

 $2.50 \pm 0.1$ 

### **Environmental Specifications**

Storage Temperature	0~35°C,≦70%RH
	3 months after shipment
Operating Temperature	-10°C to +65 °C
List Dessive Aging	100±5°C, 250 hours
Hot Passive Aging	No structural damage and functional failure
House fulfing A wine w	60°C±2°C, 90~95%R.H. 250 hours
Humidity Aging	No structural damage and functional failure
	-20±3°C, 500 hours
Cold Passive Aging	No structural damage and functional failure
	MIL-STD-202 Method 107G
Thermal Shock	+125°C /-55°C, 100 times
	No structural damage and functional failure
Solvent Resistance	MIL-STD-202, Method 215
	MIL-STD-883C, Method 2007.1, Condition A
Vibration	No structural damage and functional failure
Moisture Level Sensitivity	Level 1, J-STD-020C

### Board and Solder Layout Recommend (mm)

ß

В

A1	_
+	
а <mark>,</mark>	

**A**3

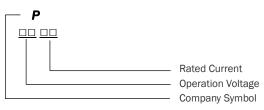
A2

Material	Glass Epoxy PCB
Base Thickness	0.6mm
Copper Thickness	0.07mm
Covered Wire	AWG8

A1	$1.30 \pm 0.1$
A2	$1.52 \pm 0.1$
A3	$7.60 \pm 0.1$

B1	3.10± 0.1
B2	$0.75 \pm 0.1$
B3	$1.95 \pm 0.1$
B4	$2.50 \pm 0.1$
B5	$2.00 \pm 0.1$
B6	$2.50 \pm 0.1$

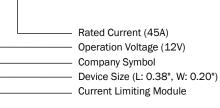
### Part Marking System





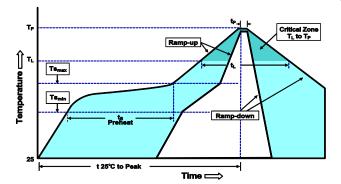
# <u>CLM 3820 P 12 45</u>

Part Number System





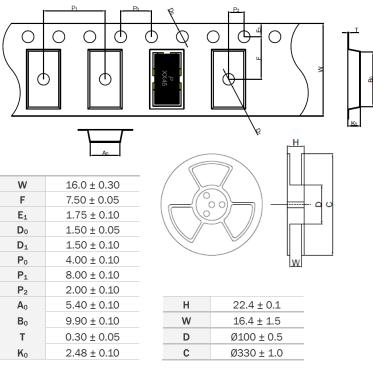
#### **Soldering Parameters**



3°C/second max.
150°C
200°C
60-120 seconds
217°C
60-105 seconds
255°C
5 seconds max.
6°C /second max.
8 minutes max.

### Tape & Reel Specification (mm.)

Devices are packaged per EIA481 and EIA-2 standard



Note 1: The temperature shown above is the top-side surface temperature of the device. Note 2: If the soldering temperature profile deviates from the recommended profile, devices may not meet the performance requirements

### **Packaging Quantity**

Part Number	Tape & Reel Quantity
CLM3820PXX45	1000

